

BondFilm® HP

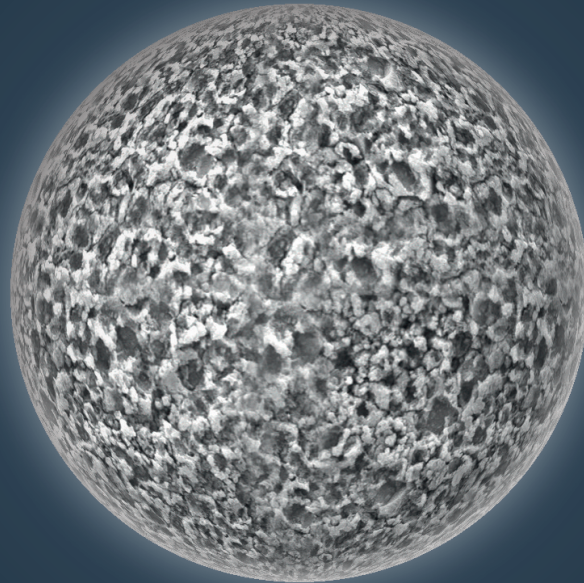
High performance bonding enhancement



Electronics

Surface treatment technology

atotech.com



Unmatched performance for the most demanding bonding applications

Up to

98%

reduction of sludge

BondFilm® HP - The epitome of modern-day oxide replacements

We can confidently say that BondFilm® HP is the best oxide replacement process on the market. The benefits of this process are manifold, but its sludge and particle reduction feature particularly stand out. Since our process is ultra clean, it ensures that the need for maintenance is minimized, thus costs are reduced, but quality and yield remain at the highest level possible.

38g/l

high copper loading capability

A worthy successor of the leading oxide replacement

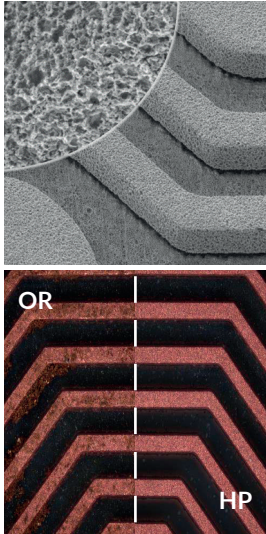


Figure 1-2:
Surface morphology and
cleanliness

Performance

Ever finer lines and spaces as well as applications that require extreme high voltages demand not only the very good adhesion performance BondFilm® is known for, but also a tremendous decrease in particle formation, to prevent high resistance shorts. BondFilm® HP is not only able to serve this demand, but also allows for a decrease in etch depth and remains very stable in its performance from the first make-up until its steady state.

Environmental impact

One of our core values at Atotech is to minimize our ecological footprint. Through considerable efforts, we have succeeded in reducing the amount of wastewater in our process, saving hundreds of filters per line every year and not making any compromises in terms of performance.

Features and benefits

- Direct drop-in to conventional oxide replacements
- Low sludge formation
- High copper loading
- Low COD/m²
- Significantly reduced downtimes
- Increased process efficiency
- Lower process costs
- Savings in wastewater

